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Qnity Introduces Enhanced Advanced Packaging Materials for Organic Interposer Applications

WILMINGTON, Del.--(BUSINESS WIRE)-- Qnity Electronics, Inc. (NYSE: Q), a premier technology solutions leader across the semiconductor value chain, today introduced enhanced advanced packaging material solutions for organic interposer applications: Intervia™ 8540HSP multi-role copper and Cyclotene™ DF6800M dry film photo-imageable dielectric. The material innovations are designed to support advanced interconnect formation, redistribution layer (RDL) designs, and emerging glass-based substrate structures.

“AI is fundamentally changing how chips are packaged—and materials have to evolve just as fast,” said Chuck Xu, President of Interconnect Solutions at Qnity. “As architectures move from shrinking to stacking, we’re focused on enabling that shift with advanced materials that give our customers a clear edge in performance, yield, and long-term reliability. Our advanced materials and process technologies enable next-generation advanced packaging applications across wafer-level packaging, panel-level packaging, and thermal and assembly.”

Qnity’s Intervia™ 8540HSP copper is engineered for advanced packaging in AI-driven GPUs, providing a high-reliability metallization solution for micro-bump and copper redistribution layer (Cu-RDL) applications. It delivers strong within-die uniformity, tight control of surface variation, and high-purity copper deposition to support consistent, fine-pitch interconnect formation required for high-performance semiconductor devices.

From its advanced packaging polymer portfolio, Qnity offers Cyclotene™ DF6800M, a dry film dielectric for glass core substrates and glass interposers. This innovation enables fine-feature patterning, effective planarization on patterned surfaces, and consistent multilayer build-up required for advanced packaging. Its photo-imageable, aqueous-developed chemistry and dry film format support efficient, scalable manufacturing of high-density semiconductor structures.

The two newly developed advanced packaging materials for interposer application will be featured at booth #2C-47 at JPCA Show 2026, June 10–12, at Tokyo Big Sight. Visitors are invited to meet Qnity experts to learn how the company is enabling next-generation AI and high-performance computing applications.

About Qnity
Qnity is a premier technology provider across the semiconductor value chain, empowering AI, high performance computing, and advanced connectivity. From groundbreaking solutions for semiconductor chip manufacturing, to enabling high-speed transmission within complex electronic systems, our high-performance materials and integration expertise make

tomorrow’s technologies possible. More information about the company, its businesses and solutions can be found at www.qnityelectronics.com.

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